

IMPORTANT NOTICE

Dear customer,

As from February 2nd 2009, ST and Ericsson have merged Ericsson Mobile Platforms and ST-NXP Wireless into a 50/50 joint venture "ST-Ericsson". As a result, the following changes are applicable to the attached document.

• Company name - ST-NXP Wireless is replaced with ST-Ericsson.

• **Copyright** - the copyright notice at the bottom of each page "© ST-NXP Wireless 200x - All rights reserved", shall now read: "© ST-Ericsson, 2009 -All rights reserved".

• *Web site* - <u>http://www.stnwireless.com</u> is replaced with <u>www.stericsson.com</u>

• **Contact information** - the list of sales offices previously obtained at <u>http://www.stnwireless.com</u>, is now found at <u>www.stericsson.com</u> under <u>Contacts</u>

If you have any questions related to the document, please contact our nearest sales office or <u>wired.support@stericsson.com</u>. Thank you for your cooperation and understanding.

AN10051 PDIUSBD12 frequently asked questions Rev. 05 — 19 February 2009

Application note

Document information

Info	Content
Keywords	pdiusbd12; usb, universal serial bus; faq
Abstract	This document contains frequently asked questions related to the PDIUSBD12.

ST-NXP Wireless

Revision history

Rev	Date	Description
05	20090219	Globally changed NXP Semiconductors and NXP to ST-NXP Wireless. Also updated the legal text.
04	20070307	Fourth release. Updated Section 1.2 and Table 1.
03	20060707	Third release. Updated Table 1.
02	20051205	Second release.
		Section 2.3: Changed the following statement under the second question from ""the device may enter test mode" to "the device will enter test mode. Also see Section 5.13."
		Added Section 5.13.
01	20051110	First release.

Contact information

For additional information, please visit: <u>http://www.stnwireless.com</u> For sales office addresses, please send an email to: <u>salesaddresses@stnwireless.com</u>

AN10051_5

Application note

1. General product information

1.1 Current consumption

How much current does the PDIUSBD12 consume?

During normal operation, the PDIUSBD12 consumes 15 mA. In suspend mode, the PDIUSBD12 internally shuts off blocks that are non-essential, allowing an operating current of 15 μ A. This is particularly important for bus-powered systems because *Universal Serial Bus Specification* requires the suspend current as 500 μ A or less. Also see <u>Section 3.1</u>.

The PDIUSBD12 offers bus-powered capability because it can go into deep sleep, drawing only 15 μ A.

1.2 USB compliance

Is the PDIUSBD12 compliant to USB 2.0?

The PDIUSBD12 is only used as a physical layer and a basic protocol layer interface. It complies with *Universal Serial Bus Specification Rev. 2.0* (full-speed).

2. Power up

2.1 Suspend output

What is the suspend output on power-up?

The SUSPEND pin is LOW right after the PDIUSBD12 is powered up.

2.2 Default clock output

What is the default clock output on power-up?

The default clock output frequency is 4 MHz.

2.3 Power-on reset

How is the power-on reset provided to the PDIUSBD12?

The PDIUSBD12 has a built-in Power-On Reset (POR) circuit. Typically, the RESET_N pin can directly be connected to V_{CC} . In applications such as Personal Digital Assistant (PDA) and Digital Still Camera (DSC), in which devices are battery operated, the PDIUSBD12 is 'always on' even when it is not in use. ElectroStatic Discharge (ESD), possibly caused by handling or storage, can cause the PDIUSBD12 to enter an indeterminate state. To avoid this, it is recommended that you use an external controlled source, such as a microcontroller or microprocessor, to provide reset to the PDIUSBD12, instead of directly connecting the PDIUSBD12 to V_{CC}. An added advantage is that reset is easily done. For example, in a PDA, the PDIUSBD12 can be reset whenever data transfer is required through the USB using HotSync application.

What must be the width of the reset pulse in the PDIUSBD12?

The external reset pulse width must be at least 500 μ s. When the RESET_N pin is LOW, ensure that the CS_N pin is in inactive state; otherwise, the device will enter test mode. Also see <u>Section 5.13</u>.

Can the PDIUSBD12 be immediately accessed after the power-on reset?

After reset, wait for at least 3 ms, before accessing the PDIUSBD12 registers. This will allow sufficient time for the crystal clock to stabilize.

3. Suspend

3.1 Suspend current ratings

What are the suspend current ratings for the PDIUSBD12?

Universal Serial Bus Specification requires bus-powered devices to draw less than 500 μ A during suspend mode. To meet this stringent requirement, the PDIUSBD12 shuts off non-essential internal blocks in suspend mode. This significantly reduces current ratings to a maximum of only 15 μ A, allowing greater margin for the rest of the hardware to meet the 500 μ A requirement in a typical bus-powered system. In addition, the PDIUSBD12 supports remote wake-up. A peripheral using the PDIUSBD12 can initiate a system wake-up as well.

Remark: The 15 μ A does not include the mandatory pull-up resistor on the D+ line that adds 200 μ A on all USB devices. Therefore, in total, using the PDIUSBD12 as a USB front-end will consume a maximum of 215 μ A on suspend. The actual measured value is 202 μ A. Also see <u>Section 1.1</u>.

3.2 Entering suspend

When does the system go into suspend?

When the host requests the system to go into suspend, or when the host itself is in suspend, USB lines are in idle mode. The electrical translation of this idle mode on the D+ and D– lines is a HIGH and a LOW, respectively. This assumes that the device has been connected to the USB bus, with a pull-up resistor on the D+ line.

In addition, when the device is unconnected, it goes into idle mode, if the D+ line is pulled to HIGH and the D– line is pulled to LOW.

With no activity on the USB bus, the PDIUSBD12 will start to count the absence of three consecutive Start-Of-Frames (SOFs) and pull the SUSPEND pin to HIGH. The corresponding SUSPEND_CHANGE bit in the Interrupt register is also set.

3.3 Exiting suspend

How does the system get out of suspend?

A USB device can get out of suspend in two ways: host initiated or device initiated.

Host initiated:

When the host recovers from a suspend state, the USB traffic becomes active again through the SOF every millisecond. The interrupt line from the PDIUSBD12 becomes active LOW to indicate that there has been a change of condition on suspend. This may be used to generate a wake-up to your microcontroller.

Device initiated:

To wake up the system using the PDIUSBD12, you can use the Send Resume command. This will toggle the D+ and D– lines to send a resume signal to the host.

3.4 V_{OUT3.3} on suspend

What is V_{OUT3.3} on suspend?

On suspend, this value drops to 2.0 V. It is, however, still capable of supplying 10 mA current.

3.5 CLKOUT frequency

What is the CLKOUT frequency during suspend?

The behavior of the output clock is configured based on the Configuration Byte written using the Set Mode command (F3h). See <u>Table 1</u>.

Table 1. Output clock behavior depending on the Configuration Byte setting

Configuration byte		CLKOUT	
No LazyClock	Clock running		
0 (on)	0 (off)	CLKOUT switches to LazyClock on suspend. The output frequency is 18 kHz to 48 kHz. The Phase-Locked Loop (PLL) clock switches off to reduce current consumption.	
1 (off)	0 (off)	CLKOUT stops on suspend. The PLL clock is off.	
0 (on)	1 (on)	CLKOUT switches to LazyClock on suspend. The output frequency is 18 kHz to 48 kHz. The PLL clock remains on.	
1 (off)	1 (on)	The suspend state does not affect the CLKOUT frequency with this configuration.	

3.6 1 M Ω resistors in USB-EPP demo

Why are the 1 M Ω resistors required in the USB-EPP demo kit?

In a self-powered system, when the USB cable is disconnected from the host, the D+ and D– lines will effectively be floating. In a noisy environment, for example, inside a scanner in which there are many high-current components, some switching will occur on the D+ and D– lines because of the induced noise. This will sometimes mislead the Serial Interface Engine (SIE) into believing that a resume signal was generated from the host, causing the PDIUSBD12 to exit the suspend state because to a false resume.

A 1 M Ω pull-down resistor is added to the D– line. Another 1 M Ω pull-up resistor is connected to the D+ line. Note that there is an error in USB-EPP kit schematics. The pull-up and pull-down resistors must follow what is mentioned here.

3.7 Behavior of the SUSPEND pin

Explain the behavior of the SUSPEND pin that is shown as an input as well as an output.

The SUSPEND pin is a bidirectional pin.

- As an input: When the PDIUSBD12 device is in suspend, the internal registers of device PDIUSBD12 cannot be accessed. If there is a need to access the device, the microcontroller can pull the SUSPEND pin to LOW to wake up the device and then access it. This is how the SUSPEND pin is used as an input.
- As an output: The PDIUSBD12 device can enter suspend as follows: When the host requests the device to go into suspend, or when the host itself is in suspend, USB

lines are in idle mode. The electrical translation of this idle mode on the D+ and D– lines is a HIGH and a LOW, respectively. This assumes that the device is connected to the USB bus with a pull-up resistor on the D+ line. In addition, when the device is unconnected, the device also goes to idle mode, if the D+ line is pulled to HIGH and the D– line is pulled to LOW. With no activity on the USB bus, the PDIUSBD12 will start to count the absence of three consecutive SOFs and pull the SUSPEND pin HIGH. This is how the SUSPEND pin is used as an output.

4. Clocking

4.1 Clockout frequency

What is the available clockout frequency?

The clockout (CLKOUT) frequency can be set through the clock division factor, using the Set Mode command (F3h). See <u>Table 2</u>.

The output frequency is based on the equation:

CLKOUT = 48 / (N + 1) MHz, where N is clock division factor

Table 2.	CLKOUT frequenc	y depending on the clock division factor
----------	-----------------	--

N clock division factor	CLKOUT
00h	48 MHz (maximum clocking frequency of the PDIUSBD12)
01h	24 MHz
02h	16 MHz
03h	12 MHz
04h	9.6 MHz
0Ah	4.36 MHz
0Bh	4 MHz (power-up value, default CLKOUT frequency, minimum clocking frequency)

4.2 Suspend CLKOUT frequency

What is the suspend CLKOUT frequency?

See <u>Section 3</u>.

4.3 Start-up time of CLKOUT

What is the start-up time of CLKOUT?

The CLKOUT frequency is derived from the oscillator: pins XTAL1 and XTAL2. The startup time for CLKOUT depends on the start-up time of the crystal oscillator. This has been measured to be typically below 2 ms. The reset circuit must be designed to be active for 2 ms to be properly reset because some microcontrollers, for example, the 8051 family, use synchronous reset.

4.4 Passive components on the crystal circuit

What are the passive components used on the crystal circuit for the PDIUSBD12?

To allow quicker starting of the clock, reduce C2 (22 pF). The jitter, however, increases as C2 is reduced. Two capacitors 22 pF and 68 pF must be used.

4.5 Clocking V_(p-p)

What is clocking $V_{(p-p)}$ to be fed to the XTAL1 pin?

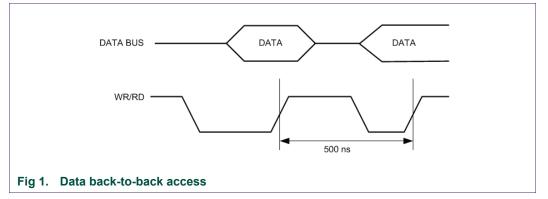
The clocking voltage can only take a peak-to-peak voltage of 3.3 V because the internal oscillator is built on a 3.3 V core. Therefore, to use a 5 V external oscillator, it must be tied to the XTAL1 pin through a 1 k Ω resistor.

5. Interfacing

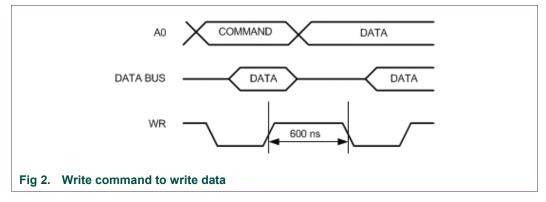
5.1 Transfer speed on the parallel interface

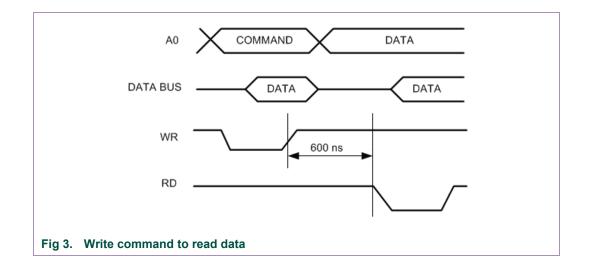
What is the fastest transfer speed achievable on the parallel interface?

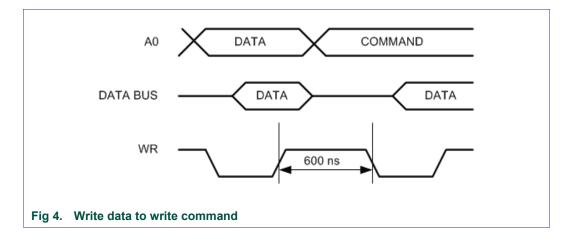
For data back-to-back access, that is, for both read and write, maintain a minimum cycle time of 500 ns. See Fig 1.

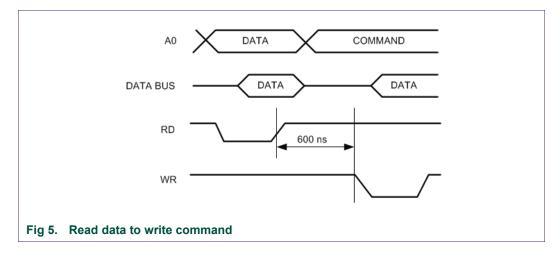


If it is from a write command to a read-or-write data, then the access time must be at least 600 ns. This also applies to a read-or-write data to a write command. See Fig 2, Fig 3, Fig 4 and Fig 5. For example, Clear Buffer or Validate Buffer.









5.2 Transferring data from host to device

How does DMA work when data is to be transferred from the host to the device?

When the PDIUSBD12 is set to DMA mode, on receiving a full packet of data from endpoint 2, DMREQ is asserted to allow the DMA controller to retrieve data from the

internal buffer of the PDIUSBD12. The DMA controller must assert the READ_N of the PDIUSBD12. The PDIUSBD12 does not have any internal buffer to keep track of how many bytes have been transferred using DMA.

5.3 Transferring data from device to host

How does DMA work when data is to be transferred from the device to the host?

When the PDIUSBD12 is set to DMA mode, there are two conditions in which data from the buffer will be transferred to the host on an IN token:

- When the internal buffer of endpoint 2 is full (64 bytes), or
- When the EOT_N signal is asserted on the last packet that is transferred through DMA.

DMREQ is asserted once the internal buffer is empty and when the DMA Enable register is set. Data is swept to the internal buffer when DMACK_N and DMREQ are both active at WR_N.

An external DMA controller generates the EOT_N signal when the data count goes to zero. If the EOT_N signal is not present, it is recommended that you have an external counter to generate EOT_N in the last packet.

5.4 Single DMA transfer and burst DMA

What is the difference between single DMA transfer mode and burst DMA mode?

The behavior of DMREQ and DMACK_N are different for single and burst modes. For graphic depiction of single and burst modes, refer to Section 15 of the *PDIUSBD12 Universal Serial Bus interface device with parallel bus* data sheet.

In single DMA transfer mode, DMREQ is asserted for every RD_N or WR_N strobe. Therefore, the number of bytes transferred can be counted based on the falling edge of DMREQ.

In burst DMA mode, DMREQ is asserted through the burst length that is defined based on the DMA burst information given in the Set DMA command (FBh).

Table 3. DMA configuration register setting

DMA configuration register Remarks

Bit 1	Bit 0	-
0	0	Single DMA transfer mode
0	1	Burst DMA mode. Four bytes of data transferred on every assertion of DMREQ, unless prematurely ended by EOT_N.
1	0	Burst DMA mode. Eight bytes of data transferred on every assertion of DMREQ, unless prematurely ended by EOT_N.
1	1	Burst DMA mode. 16 bytes of data transferred on every assertion of DMREQ, unless prematurely ended by EOT_N.

5.5 PDIUSBD12 voltage input

Does the PDIUSBD12 take 5 V or 3.3 V input?

The PDIUSBD12 can take either 5 V or 3.3 V input. To operate the IC at 5 V, supply a 5 V voltage to the V_{CC} pin only and leave the VOUT3.3 pin open, decoupled with capacitor. To operate the IC at 3.3 V, supply a 3.3 V voltage to both the V_{CC} and VOUT3.3 pins.

5.6 Output voltage swing

What is the output voltage swing?

There are typically two output types on the PDIUSBD12: open drain and normal driving. The driving strength for each is specified in the data sheet. The voltage swing of an open-drain output depends on the pull-up resistor on which it is tied.

<u>Table 4</u> shows the voltage swing when pin V_{CC} of the PDIUSBD12 is powered from 5 V.

Table 4. Voltage swing based on 5 V Pin name Description Voltage swing Туре DATA[7:0] 102 Input or output with driving strength of 2 mA 5 V SUSPEND OD4 Open-drain, can sink 4 mA Depends on pull-up 5 V CLKOUT 02 Output with 2 mA drive INT N OD4 Open-drain, can sink 4 mA Depends on pull-up GL N OD8 Open-drain, can sink 8 mA Not applicable DMREQ 04 Output with 4 mA drive 5 V

<u>Table 5</u> shows the voltage swing when the V_{CC} pin of the PDIUSBD12 is powered from 3.3 V.

Table 5. Voltage swing based on 3.3 V Pin name Description Voltage swing Type DATA[7:0] 102 Input or output with driving strength of 2 mA 3.3 V SUSPEND OD4 Open-drain, can sink 4 mA Depends on pull-up CLKOUT 02 Output with 2 mA drive 3.3 V INT_N OD4 Open-drain, can sink 4 mA Depends on pull-up GL N OD8 Open-drain, can sink 8 mA Not applicable

Remark: When V_{CC} of the PDIUSBD12 is powered from 3.3 V, the internal regulator shuts off. All voltage regulation must be done externally. Therefore, a 3.3 V source must be applied to both the V_{CC} and VOUT3.3 pins.

DMREQ

04

Output with 4 mA drive

3.3 V

5.7 Using VOUT3.3 to drive other parts of the circuit

Can I use VOUT3.3 to drive other parts of my circuit?

The VOUT3.3 pin is provided to supply the pull-up voltage of 1.5 k Ω resistor. You can also opt to use the internal SoftConnect¹ resistor. Loading the VOUT3.3 pin apart from this resistor is not recommended.

5.8 CS_N and DACK_N

Can CS_N and DACK_N be active at the same time?

Do not write or read by asserting CS_N during DMA when DACK_N is active.

5.9 Level trigger or edge trigger

Should level trigger or edge trigger be used on the PDIUSBD12?

The PDIUSBD12 INTERRUPT pin remains LOW as long as the Interrupt register is nonzero. Therefore, the microcontroller must be configured to be level trigger on interrupt.

5.10 V_{BUS} sensing functionality

How must EOT_N be connected to accomplish a V_{BUS} sensing functionality?

In a self-powered system, when the USB connection is removed, there may not be any indication to the microcontroller that the USB cable is disconnected. To detect a disconnection, the EOT_N pin has dual functionality, that is, to function as an EOT (End-Of-Transfer) during DMA mode and to detect V_{BUS} sensing. V_{BUS} is the 5 V power supply pin from the USB connector. For the V_{BUS} sensing, EOT_N is connected to V_{BUS} through a 1 k Ω resistor and a 1 M Ω bleeding resistor to leak charges. This is to ensure that EOT_N goes to zero when V_{BUS} is removed.

So, when the device is in self-powered mode and when the host is off, even if the USB cable is connected, the device will check the non-availability of V_{BUS} through the EOT_N pin, and switch off the internal SoftConnect resistor. This ensures that the PDIUSBD12 is disconnected and does not unnecessarily power the D+ line.

5.11 ALE

How to use the ALE pin of the PDIUSBD12?

When the ALE pin of the PDIUSBD12 is connected to the ALE pin of the microcontroller, and the address bus and the data bus are multiplexed, this pin is used by the internal logic to strobe in information to differentiate between command and data on the parallel bus. An even address means writing data to or reading data from the PDIUSBD12, and an odd address means writing command to the PDIUSBD12. CS_N must be pulled to LOW during data communications.

A0 will not be used and must be connected to HIGH in this instance.

5.12 CS_N

Can the CS_N pin of the PDIUSBD12 be connected to ground all the time?

The PDIUSBD12 must be treated like any other microprocessor-based device. CS_N is connected so that the PDIUSBD12 can share the system bus with other devices. In some instance, CS_N may be grounded all the time. For example, when the PDIUSBD12 is the only device residing on the system bus. If the system bus is shared, additional circuitry

¹ SoftConnect is a trademark of ST-NXP Wireless.

may be required to separate the PDIUSBD12 from other resources through RD_N/WR_N, if CS_N must be grounded.

Example: To glue MC68331 with the PDIUSBD12, the t_{RHCH} and t_{WHCH} timing for the chip select output must be delayed to match the timing of the PDIUSBD12. In this instance, CS_N of the PDIUSBD12 can be grounded, and RD_N/WR_N may be all you need. To separate other devices that share the same bus, glue logic can be implemented on RD_N/WR_N that is going to the PDIUSBD12.

5.13 Entering test mode

How can the PDIUSBD12 enter test mode?

The PDIUSBD12 will enter test mode when either of these conditions is met:

- When the RESET_N pin is LOW and the CS_N pin is toggled, or
- When the CS_N pin is LOW and the RESET_N pin is toggled.

Therefore, to prevent the PDIUSBD12 from entering test mode, make sure that when the RESET_N pin is LOW, the CS_N pin is in inactive state. Similarly, when the CS_N pin is LOW, the RESET_N pin is in inactive state.

6. Programming the PDIUSBD12

6.1 SoftConnect

What is SoftConnect?

The Set Mode register at F3h has a bit that directly connects to the pull-up resistor on the D+ USB line. When the bit is logic 1, it means that the pulled-up resistor is enabled. Therefore, a host or a hub will detect that something is plugged on its USB port, even though it has physically been connected before the command was issued.

SoftConnect allows the microcontroller to finish its initialization routine before notifying the host of its presence. This is especially valuable in a bus-powered device in which the 5 V power supply must first be stable before enumeration.

To force the host to perform re-enumeration, the microcontroller can initiate a soft disconnect by setting the Set Mode SoftConnect bit to logic 0. In doing so, the host is forced to reload the host device driver, allowing a device initiated upgrade without user intervention to disconnect and connect the USB cable.

6.2 Set address or enable

What is the difference between set address or enable and SoftConnect?

The set address or enable is required to enable the SIE to respond to the USB request that is directed towards the address preset through the set address or enable. Without enabling, the PDIUSBD12 will not respond with an ACK or NAK token, even though the request is directed to its preset address.

6.3 Configuring the DMA register

How to configure the DMA register?

On power-up, the DMA register may be used to check for read or write error. It is the only register that is available to read and write. Note that on power-up, the auto-reload bit cannot be set, and the DMA enable bit when set does not pull up the DMREQ pin.

7. Others

7.1 Double buffering

What is double buffering?

Double buffering on endpoint 2 allows data to be source or sink on the USB bus while the internal buffer is being read or written by the microcontroller or the DMA controller. This increases the overall throughput because the host does not need to wait for the internal buffer to be cleared or filled before feeding or extracting the next packet.

When data is to be extracted from the USB device to the host, the switching from one buffer that was filled up by the microcontroller to the sending buffer at the USB end is done transparent to the microcontroller. The microcontroller does not need to keep track of which buffer to use because it always uses the same register to access the IN buffer.

When data is to be received from the host to the USB device, the switching from one buffer that was read by the microcontroller to the receiving buffer at the USB end is done transparent to the microcontroller. The microcontroller does not need to keep track of which buffer to use because it always uses the same register to access the OUT buffer.

7.2 Internal buffer size

What is the internal buffer size of the PDIUSBD12?

The total number of bytes of the internal buffer dedicated for USB transfer is 320 bytes.

Table 6. Internal buffer size						
Total bytes		Endpoint 0		Endpoint 1		Endpoint 2
320	=	16 (IN) + 16 (OUT)	+	16 (IN) + 16 (OUT)	+	[16 (IN) + 16 (OUT)] x 2 (double buffered)

7.3 EMI issues

Are there any EMI issues that need to be taken into consideration?

ElectroMagnetic Interference (EMI) issues are very broad subject to be covered in this document. In general, add ferrite beads on V_{BUS} and the ground at the input side of the USB connector. One such part is BLM32A07.

It is recommended that you have capacitive coupling from the USB shield to the electrical ground.

7.4 Resistor value for the GoodLink² LED

What resistor value is recommended for the GoodLink LED?

This depends on brightness of the LED that you want, and also on the brightness and current rating of the LED. Any value from 100 Ω to 1 k Ω is normally acceptable. The evaluation kit recommends a value of 470 Ω .

AN10051

PDIUSBD12 FAQs

² GoodLink is a trademark of ST-NXP Wireless.

7.5 Vendor ID and Product ID

What are the Vendor ID and the Product ID?

The Vendor ID (VID) identifies the manufacturer of the USB product. It is used to load the INF file that contains the text string of the manufacturer and information on which device driver to load on Microsoft Windows operating system.

The VID can be obtained by registering with USB-IF. The VID for ST-NXP Wireless is 0471.

The Product ID (PID) is unique to each USB product.

The VID and PID can be set by changing the device descriptors in firmware. This is good for product differentiation as customers maintain their own product identity on Windows operating system.

7.6 6 MHz crystal

Why is the PDIUSBD12 implemented based on a 6 MHz crystal?

The 6 MHz crystal lowers the risk of having EMI problems during production.

7.7 D12Test.exe report

Why does ST-NXP Wireless test application D12Test.exe report a varying data transfer rate?

The calculation of the real-time transfer rate is made on every block of 16 kB. The actual derivation formula used is:

Transfer speed $(B/s) = 16 \times 1024 / time spent (seconds).$

Where time spent is the completion time of transfer minus the initiated time. The Microsoft Windows 98 operating system provides a 1 ms resolution on time spent. In addition, a random overhead is incurred because of system calls from user mode to kernel mode. In total, a 2 ms ambiguity will put the variance of the transfer rate as about 20 %.

Whatever the reported transfer rate, often the host is the bottleneck. A LeCroy analyzer can be used to verify that the PDIUSBD12 is fully utilizing the allocation provide by the host.

7.8 Isochronous and bulk pipe

What is the allocation difference between an isochronous and bulk pipe?

An isochronous pipe guarantees bandwidth, regardless of data integrity. A bulk pipe guarantees data integrity, but delivery is based on 'first require, first allocate'. Therefore, on a heavy USB traffic, the bulk pipe may be starved.

7.9 Implications of adding 1 MΩ leaking resistors

Are there any implications on the signaling quality on adding 1 M Ω leaking resistors on the PDIUSBD12 demo board?

All the signals on the physical layer of USB are designed to be single-end terminated. At any one time, there can only be a transmitter and a receiver. The transmitter, or the driver, is required to have an output impedance of between 28 Ω and 44 Ω . At the receiving end, the receiver must present an input impedance of greater than 300 k Ω , excluding termination.

When the PDIUSBD12 is in the driving state, the output impedance is between 29 Ω and 44 Ω . The effective impedance, inclusive of the parallel pull-up at D+ of 1.5 k Ω and the parallel pull-down at D+ and D- of 1 M Ω , does not vary much with the driving impedance.

During receiving state, the total impedance is greater than 300 k Ω , even with the 1 M Ω leakage resistor is present.

7.10 Matching resistor values for D+ and D-

What values of matching resistors must be used for the D+ and D- lines?

Fig 6. Matching resistor on the D+ and D- lines

Place 18 Ω resistor in series on the D+ and D– lines.

7.11 Chip ID

What is the command to read the chip ID of the PDIUSBD12 and what is the chip ID?

The command to read the chip ID of the PDIUSBD12 is FDh and the expected value is 1012h.

7.12 Crystal specification

What is the crystal specification of the PDIUSBD12?

The crystal specification fundamental:

- Temperature range:
 - ±50 ppm (-20 °C to +70 °C)
- Accuracy:

±50 ppm at +25 °C temperature

- R1: series resistance, C_p: shunt capacitance, C_L: load capacitance
 6 MHz fundamental
 - o MHZ fundamen

R1 < 100 Ω,

C_p < 7 pF

 C_L = 8 pF Cx1 = 15 pF, Cx2 = 15 pF

- 12 pF Cx1 = 22 pF, Cx2 = 22 pF
 - 18 pF Cx1 = 33 pF, Cx2 = 33 pF

8. Legal information

Please Read Carefully:

Information in this document is provided solely in connection with ST-NXP products. ST-NXP Wireless NV and its subsidiaries ("ST-NXP") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST-NXP products are sold pursuant to ST-NXP's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST-NXP products and services described herein, and ST-NXP assumes no liability whatsoever relating to the choice, selection or use of the ST-NXP products and services described herein. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST-NXP for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST-NXP'S TERMS AND CONDITIONS OF SALE ST-NXP DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST-NXP PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST-NXP REPRESENTATIVE, ST-NXP PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST-NXP PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST-NXP products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST-NXP for the ST-NXP product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST-NXP.

ST-NXP and the ST-NXP logo are trademarks or registered trademarks of ST-NXP in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST-NXP logo is a registered trademark of ST-NXP Wireless. All other names are the property of their respective owners.

© 2009 ST-NXP Wireless - All rights reserved

ST-NXP Wireless group of companies

Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - India - Italy - Japan - Korea - Malaysia - Mexico -Netherlands - Singapore - Sweden - Switzerland - Taiwan - United Kingdom - United States of America

www.stnwireless.com

AN10051 PDIUSBD12 FAQs

9. Contents

1.1Current consumption31.2USB compliance32.Power up32.1Suspend output32.2Default clock output32.3Power-on reset33.Suspend43.1Suspend current ratings43.2Entering suspend43.3Exiting suspend43.4Vour3.3 on suspend53.5CLKOUT frequency53.61 MΩ resistors in USB-EPP demo53.7Behavior of the SUSPEND pin53.6Clocking64.1Clockout frequency64.2Suspend CLKOUT frequency64.3Start-up time of CLKOUT64.4Passive components on the crystal circuit75.5Interfacing75.1Transfer speed on the parallel interface75.2Transferring data from host to device85.3Transferring data from device to host95.4Single DMA transfer and burst DMA95.5PDIUSBD12 voltage input105.6Output voltage swing105.7Using VOUT3.3 to drive other parts of the circuit5.8S.N and DACK_N115.9Level trigger or edge trigger115.10V _{BUS} sensing functionality115.11ALE115.12CS_N115.13Entering test mode12
2.Power up32.1Suspend output32.2Default clock output32.3Power-on reset33.Suspend43.1Suspend current ratings43.2Entering suspend43.3Exiting suspend43.4Vout3.3 on suspend53.5CLKOUT frequency53.61 M Ω resistors in USB-EPP demo53.7Behavior of the SUSPEND pin54.Clocking64.1Clockout frequency64.2Suspend CLKOUT frequency64.3Start-up time of CLKOUT64.4Passive components on the crystal circuit75.Interfacing75.1Transfer speed on the parallel interface75.2Transferring data from host to device85.3Transferring data from device to host95.4Single DMA transfer and burst DMA95.5PDIUSBD12 voltage input105.6Output voltage swing105.7Using VOUT3.3 to drive other parts of the circuit115.8CS_N and DACK_N115.9Level trigger or edge trigger115.10V _{BUS} sensing functionality115.11ALE115.12CS_N115.13Entering test mode12
2.1 Suspend output 3 2.2 Default clock output 3 2.3 Power-on reset 3 3. Suspend 4 3.1 Suspend current ratings 4 3.2 Entering suspend 4 3.3 Exiting suspend 4 3.4 Vout3.3 on suspend 5 3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo 5 3.7 Behavior of the SUSPEND pin 5 3.6 Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5. Clocking V _(P-P) 7 5. Interfacing 7 5.1 Transferring data from host to device 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10
2.2 Default clock output 3 2.3 Power-on reset 3 3. Suspend 4 3.1 Suspend current ratings 4 3.2 Entering suspend 4 3.3 Exiting suspend 4 3.4 Vout3.3 on suspend 5 3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo 5 3.7 Behavior of the SUSPEND pin 5 3.6 Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5. Clocking V _(P-P) 7 5. Interfacing 7 5.1 Transferring data from host to device 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10
2.3Power-on reset33.Suspend43.1Suspend current ratings43.2Entering suspend43.3Exiting suspend43.4 $V_{OUT3.3}$ on suspend53.5CLKOUT frequency53.61 M\Omega resistors in USB-EPP demo53.7Behavior of the SUSPEND pin54.Clocking64.1Clockout frequency64.2Suspend CLKOUT frequency64.3Start-up time of CLKOUT64.4Passive components on the crystal circuit75.Interfacing75.1Transfer speed on the parallel interface75.2Transferring data from host to device85.3Transferring data from device to host95.4Single DMA transfer and burst DMA95.5PDIUSBD12 voltage input105.6Output voltage swing105.7Using VOUT3.3 to drive other parts of the circuit115.8CS_N and DACK_N115.9Level trigger or edge trigger115.10V _{BUS} sensing functionality115.11ALE115.12CS_N115.13Entering test mode12
3. Suspend 4 3.1 Suspend current ratings 4 3.2 Entering suspend 4 3.3 Exiting suspend 4 3.4 Vout33 on suspend 5 3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo 5 3.7 Behavior of the SUSPEND pin 5 4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit. 7 5.1 Interfacing 7 5.2 Transfer speed on the parallel interface 7 5.3 Transferring data from host to device. 8 5.3 Transferring data from device to host. 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit
3.1 Suspend current ratings 4 3.2 Entering suspend 4 3.3 Exiting suspend 4 3.4 VouT3.3 on suspend 5 3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo 5 3.7 Behavior of the SUSPEND pin 5 4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit. 7 5. Interfacing 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device. 8 5.3 Transferring data from device to host. 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit
3.2 Entering suspend 4 3.3 Exiting suspend 4 3.4 V _{OUT3.3} on suspend 5 3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo. 5 3.7 Behavior of the SUSPEND pin 5 4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5.1 Interfacing 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit
3.3 Exiting suspend 4 3.4 V _{OUT3.3} on suspend 5 3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo 5 3.7 Behavior of the SUSPEND pin 5 4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5.1 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5.5 Clocking V _(P-P) 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device. 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit 11 5.8 CS_N and DACK_N <td< td=""></td<>
3.4 V _{OUT3.3} on suspend 5 3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo. 5 3.7 Behavior of the SUSPEND pin 5 4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit. 7 5. Interfacing 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device. 8 5.3 Transferring data from device to host. 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit 11 5.8 CS_N and DACK_N 11 5.9 Level trigger or edge trigger 11 5.10 V _{BUS} sensing functionality 11 5.11 ALE 11
3.5 CLKOUT frequency 5 3.6 1 MΩ resistors in USB-EPP demo. 5 3.7 Behavior of the SUSPEND pin 5 4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit. 7 5. Interfacing 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device. 8 5.3 Transferring data from device to host. 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit 11 5.8 CS_N and DACK_N 11 5.9 Level trigger or edge trigger 11 5.10 V _{BUS} sensing functionality 11 5.11 ALE 11 5.12 CS_N 11
3.6 1 MΩ resistors in USB-EPP demo
3.7 Behavior of the SUSPEND pin 5 4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5. Interfacing 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit 11 5.8 CS_N and DACK_N 11 5.9 Level trigger or edge trigger 11 5.10 V _{BUS} sensing functionality 11 5.11 ALE 11 5.12 CS_N 11 5.13 Entering test mode 12
4. Clocking 6 4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5. Interfacing 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit 11 5.8 CS_N and DACK_N 11 5.9 Level trigger or edge trigger 11 5.10 V _{BUS} sensing functionality 11 5.11 ALE 11 5.12 CS_N 11 5.13 Entering test mode 12
4.1 Clockout frequency 6 4.2 Suspend CLKOUT frequency 6 4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit 7 5. Clocking V _{(P-P}) 7 5. Interfacing 7 5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit 11 5.8 CS_N and DACK_N 11 5.9 Level trigger or edge trigger 11 5.10 V _{BUS} sensing functionality 11 5.11 ALE 11 5.12 CS_N 11 5.13 Entering test mode 12
4.2 Suspend CLKOUT frequency
4.3 Start-up time of CLKOUT 6 4.4 Passive components on the crystal circuit
4.4Passive components on the crystal circuit74.5Clocking $V_{(p-p)}$ 75.Interfacing75.Interfacing data from host to device75.1Transfer speed on the parallel interface
4.5Clocking $V_{(p-p)}$ 75.Interfacing75.1Transfer speed on the parallel interface75.2Transferring data from host to device85.3Transferring data from device to host95.4Single DMA transfer and burst DMA95.5PDIUSBD12 voltage input105.6Output voltage swing105.7Using VOUT3.3 to drive other parts of the circuit115.8CS_N and DACK_N115.9Level trigger or edge trigger115.10V_BUS sensing functionality115.11ALE115.12CS_N115.13Entering test mode12
5. Interfacing
5.1 Transfer speed on the parallel interface 7 5.2 Transferring data from host to device 8 5.3 Transferring data from device to host 9 5.4 Single DMA transfer and burst DMA 9 5.5 PDIUSBD12 voltage input 10 5.6 Output voltage swing 10 5.7 Using VOUT3.3 to drive other parts of the circuit 11 5.8 CS_N and DACK_N 11 5.9 Level trigger or edge trigger 11 5.11 ALE 11 5.12 CS_N 11 5.13 Entering test mode 12
5.2 Transferring data from host to device
5.3 Transferring data from device to host
5.4 Single DMA transfer and burst DMA
5.5 PDIUSBD12 voltage input
5.6 Output voltage swing
5.7 Using VOUT3.3 to drive other parts of the circuit 11 11 5.8 CS_N and DACK_N 5.9 Level trigger or edge trigger 5.10 V _{BUS} sensing functionality 5.11 ALE 5.12 CS_N 5.13 Entering test mode
11 5.8 CS_N and DACK_N 5.9 Level trigger or edge trigger 5.10 V _{BUS} sensing functionality 5.11 ALE 5.12 CS_N 5.13 Entering test mode
5.8 CS_N and DACK_N 11 5.9 Level trigger or edge trigger 11 5.10 V _{BUS} sensing functionality 11 5.11 ALE 11 5.12 CS_N 11 5.13 Entering test mode 12
5.9 Level trigger or edge trigger 11 5.10 V _{BUS} sensing functionality 11 5.11 ALE 11 5.12 CS_N 11 5.13 Entering test mode 12
5.10 V _{BUS} sensing functionality
5.11 ALE 11 5.12 CS_N 11 5.13 Entering test mode 12
5.12 CS_N
5.13 Entering test mode
g
6. Programming the PDIUSBD1212
6.1 SoftConnect
6.2 Set address or enable
6.3 Configuring the DMA register
7. Others
7.1 Double buffering
7.2 Internal buffer size
7.3 EMI issues
7.4 Resistor value for the GoodLink LED

7.5	Vendor ID and Product ID14
7.6	6 MHz crystal14
7.7	D12Test.exe report14
7.8	Isochronous and bulk pipe14
7.9	Implications of adding 1 M Ω leaking resistors14
7.10	Matching resistor values for D+ and D15
7.11	Chip ID15
7.12	Crystal specification15
8.	Legal information16
9.	Contents17

Please be aware that important notices concerning this document and the product(s) described herein, have been included in the section 'Legal information'.

$\ensuremath{\mathbb{C}}$ ST-NXP Wireless 2009. All rights reserved.

For more information, please visit: http://www.stnwireless.com For sales office addresses, email to: salesaddresses@stnwireless.com